

THIN FILM MAGNETIC HEAD

ABSTRACT OF THE DISCLOSURE

A magnetic material having a low coefficient of thermal expansion of $11.5 \times 10^{-6}/\text{K}$ or less is used for forming at least one of a lower shield or an upper shield. A laminated film comprising a layer of the magnetic material having a low coefficient of thermal expansion of $11.5 \times 10^{-6}/\text{K}$ or less, and an 80 wt% NiFe alloy layer, is used for forming at least one of the lower shield and the upper shield. Thus, the thin film magnetic head having reduced after-record noise and reduced thermal protrusion can be obtained.

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